

● General Description

The AGM14N10MNA combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

This device is ideal for load switch and battery protection applications.

● Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance
- 100% Avalanche tested
- 100% DVDS tested

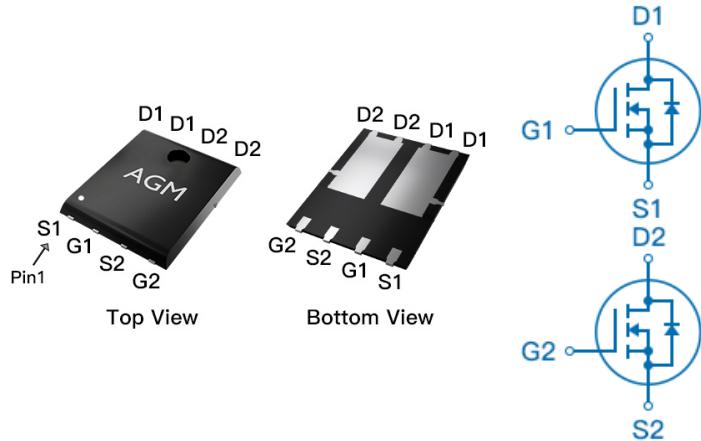
● Application

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

Product Summary

BVDSS	RDS(on)	ID
100V	13mΩ	50A

PDFN5*6 Pin Configuration



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AGM14N10MNA	AGM14N10MNA	PDFN5*6	330mm	12mm	3000

Table 1. Absolute Maximum Ratings (TA=25°C)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	100	V
VGS	Gate-Source Voltage (VDS=0V)	±20	V
ID	Drain Current-Continuous(Tc=25°C) (Note 1)	50	A
	Drain Current-Continuous(Tc=100°C)	35	A
IDM (pulse)	Drain Current-Pulsed (Note 2)	200	A
PD	Maximum Power Dissipation(Tc=25°C)	70	W
	Maximum Power Dissipation(Tc=100°C)	28	W
EAS	Avalanche energy (Note 3)	64	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	°C

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
R _{θJA}	Thermal Resistance Junction-ambient (Steady State) ¹	---	20	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	1.78	°C/W

Table 3. N- Channel Electrical Characteristics (TJ=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=250μA	100	--	--	V
IDSS	Zero Gate Voltage Drain Current	VDS=100V, VGS=0V	--	--	1	μA
IGSS	Gate-Body Leakage Current	VGS=±20V, VDS=0V	--	--	±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS, ID=250μA	1.2	--	2.2	V
gFS	Forward Transconductance	VDS=5V, ID=8A	--	8.0	--	S
RDS(on)	Drain-Source On-State Resistance	VGS=10V, ID=10A	--	13	16	mΩ
		VGS=4.5V, ID=8A	--	16	20	mΩ

Dynamic Characteristics

Ciss	Input Capacitance	VDS=40V, VGS=0V, F=1MHZ	--	930	--	pF	
Coss	Output Capacitance		--	315	--	pF	
Crss	Reverse Transfer Capacitance		--	2.5	--	pF	
Rg	Gate resistance	VGS=0V, VDS=0V, f=1.0MHz		--	6.0	--	Ω

Switching Times

td(on)	Turn-on Delay Time	VGS=10V, VDS=50V, ID=10A, RGEN=1.6Ω	--	6.0	--	nS
tr	Turn-on Rise Time		--	2.0	--	nS
td(off)	Turn-Off Delay Time		--	18	--	nS
tf	Turn-Off Fall Time		--	2.0	--	nS
Qg	Total Gate Charge	VGS=10V, VDS=50V, ID=10A	--	16.5	--	nC
Qgs	Gate-Source Charge		--	3.0	--	nC
Qgd	Gate-Drain Charge		--	3.1	--	nC

Source-Drain Diode Characteristics

ISD	Source-Drain Current(Body Diode)		--	--	50	A
VSD	Forward on Voltage	VGS=0V, IS=10A	--	--	1.2	V
trr	Reverse Recovery Time	IF=10A , dI/dt=100A/μs , TJ=25°C	--	40	--	ns
Qrr	Reverse Recovery Charge		--	52	--	nc

Notes 1.The maximum current rating is package limited.

Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature.

Notes 3.EAS condition: TJ=25°C

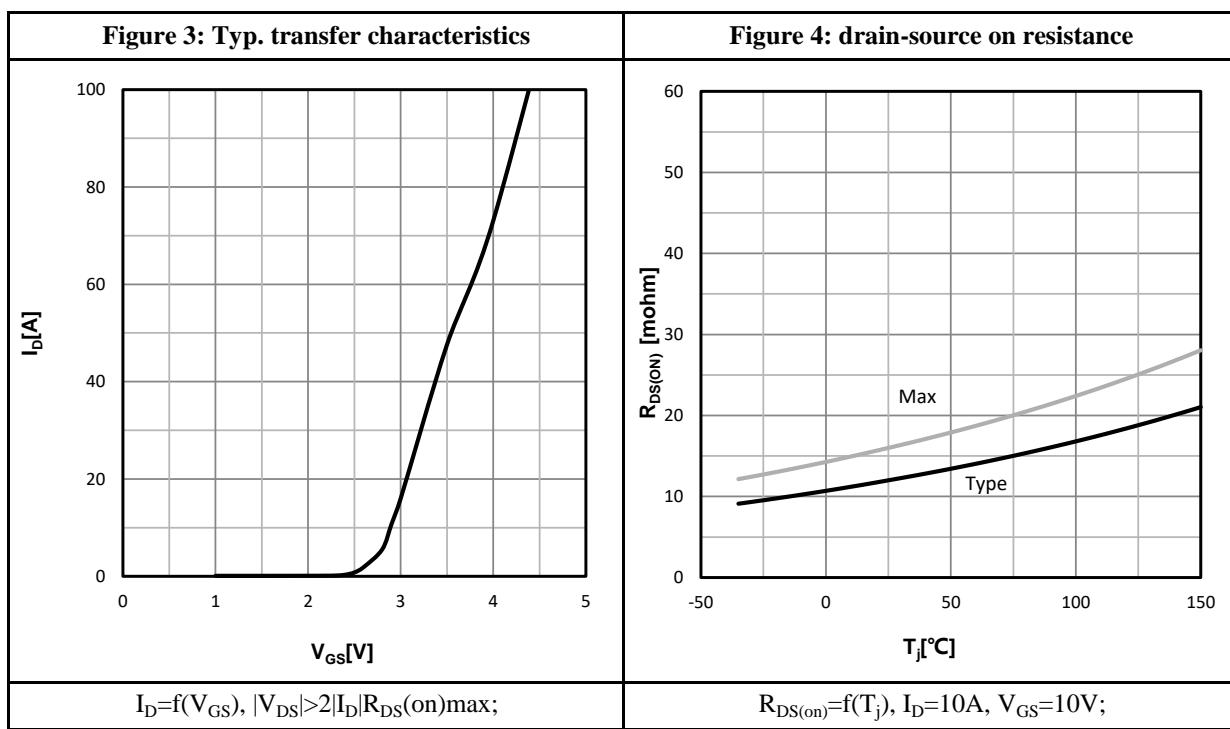
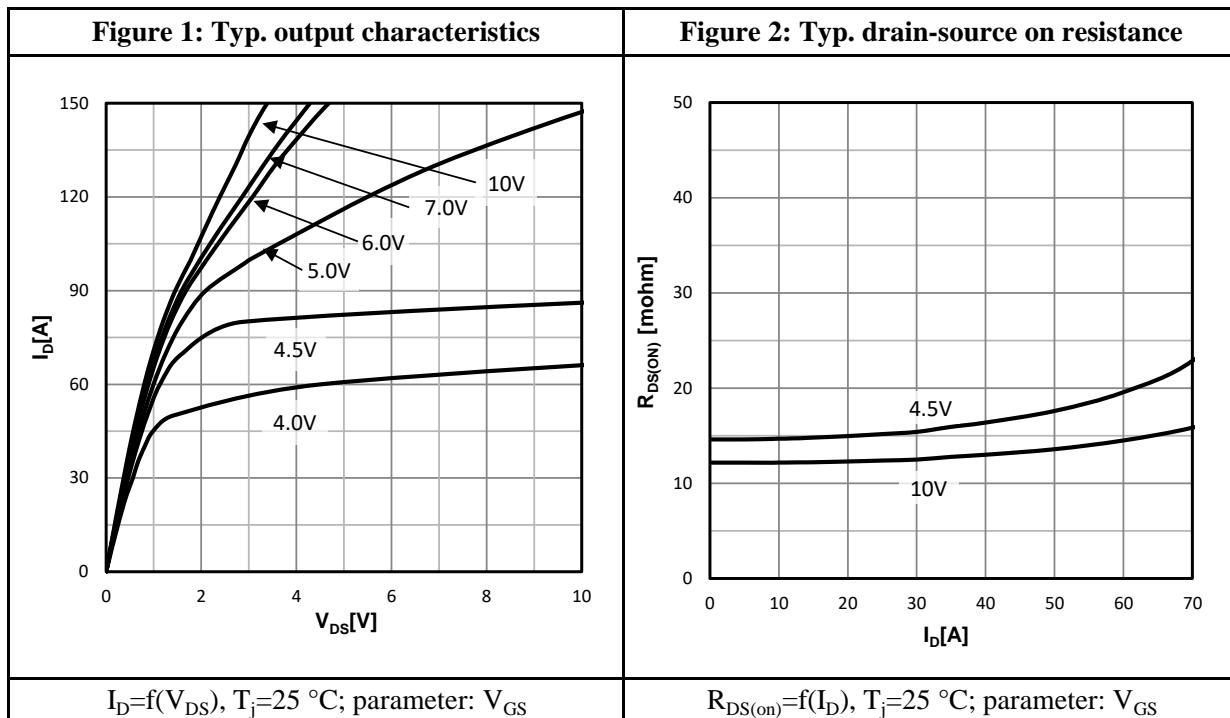
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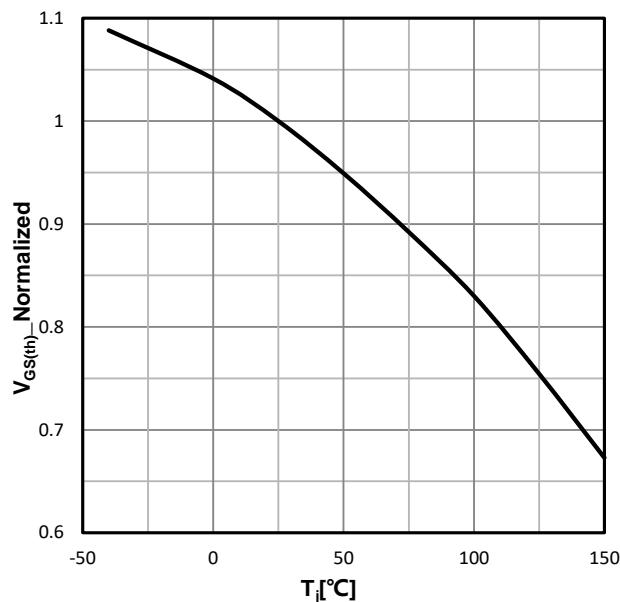
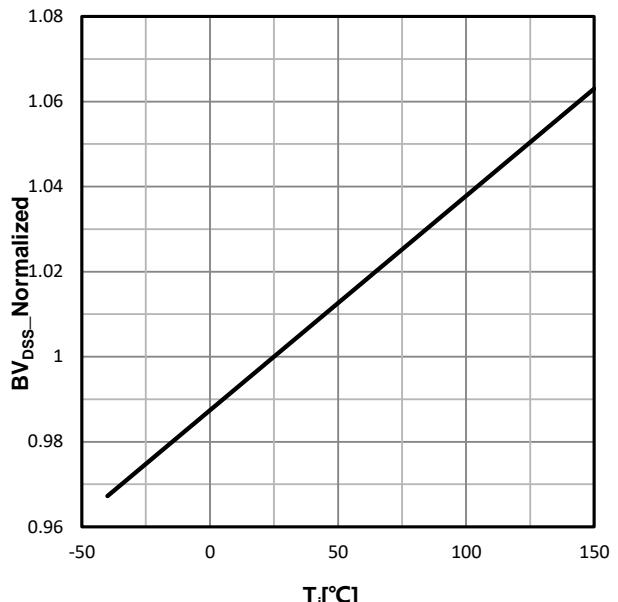
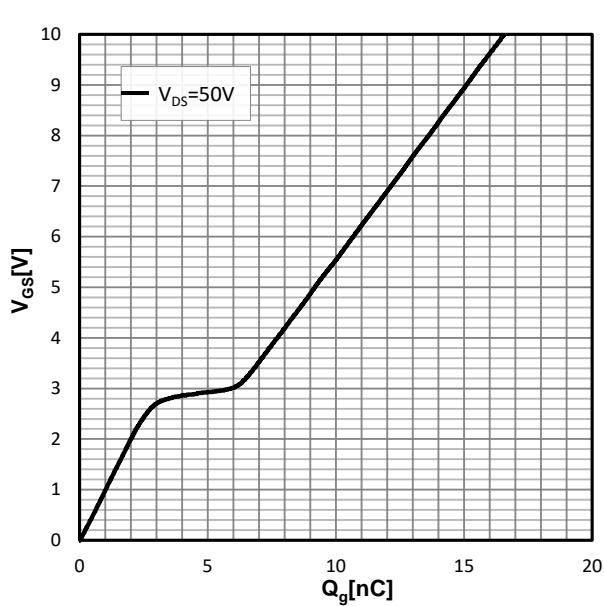
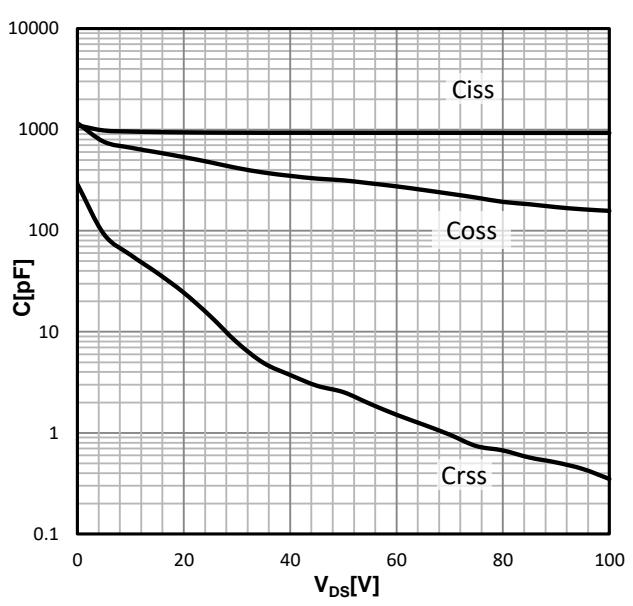
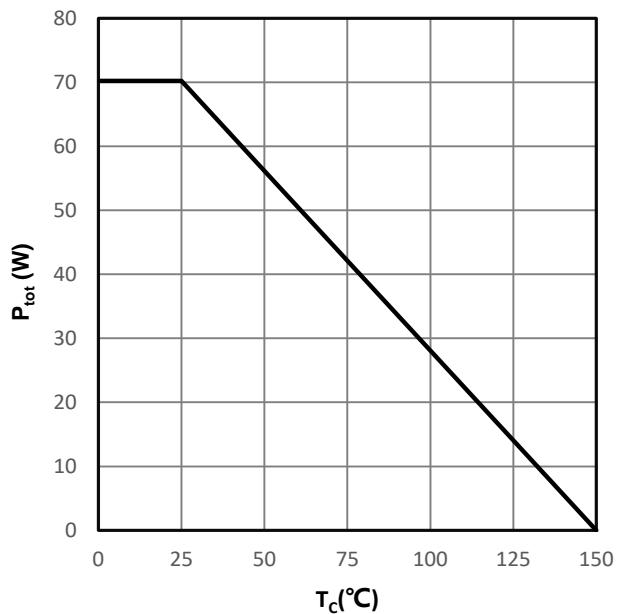
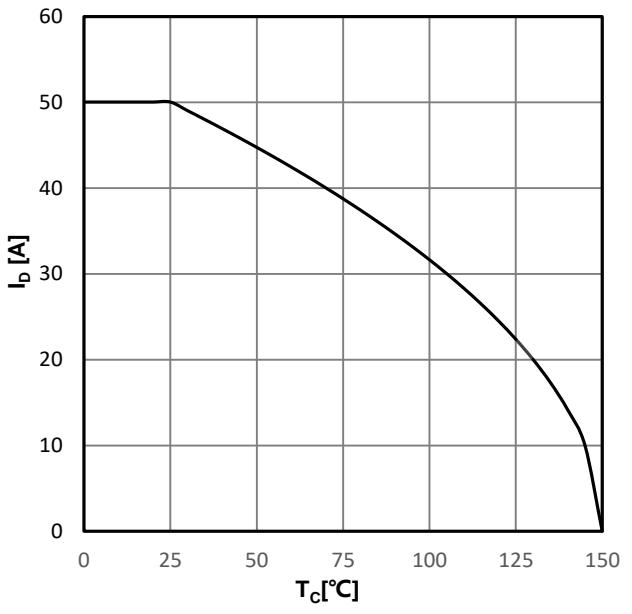
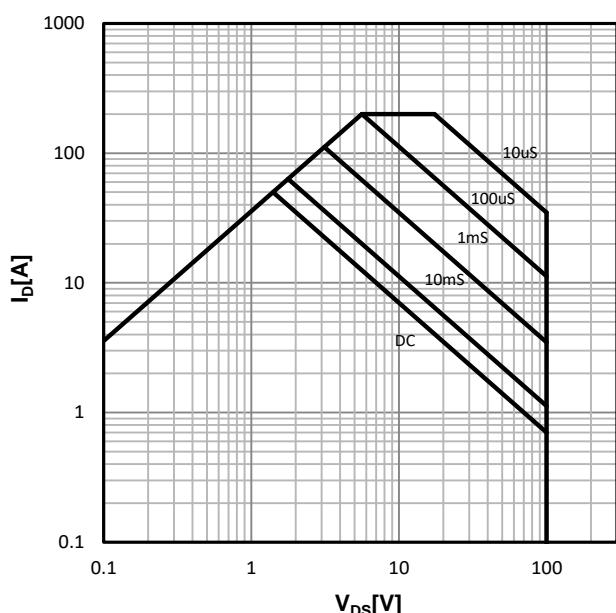
Figure 5: Typ. gate threshold voltage
 $V_{GS}=f(T_j), I_{DSS}=V_{DS}, I_D=250\mu\text{A};$
Figure 6: Drain-source breakdown voltage
 $V_{BR(DSS)}=f(T_j); I_D=250\mu\text{A};$
Figure 7: Typ. gate charge
 $V_{GS}=f(Q_g), I_D=10\text{A}, T_j=25\text{ °C}; \text{ parameter: } V_{DS}$
Figure 8: Typ. Capacitances
 $C=f(V_{DS}); V_{GS}=0\text{V}; f=1.0\text{ MHz};$

Figure 9: Power dissipation

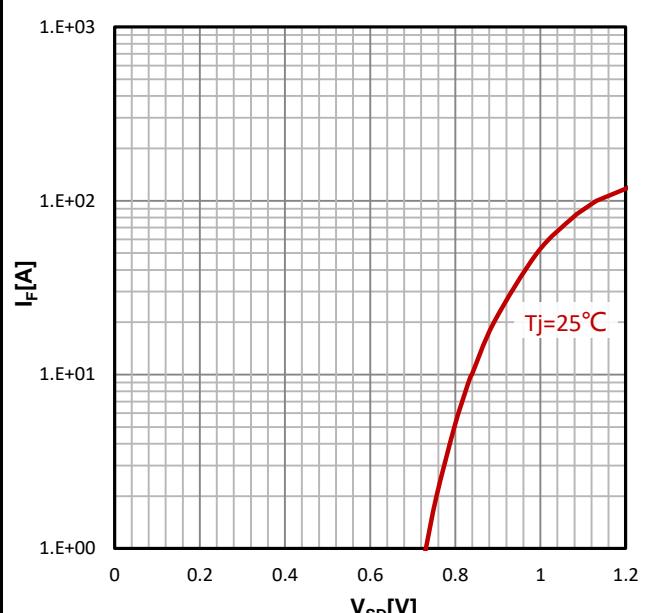
$$P_{tot}=f(T_C);$$

Figure 10: Drain current

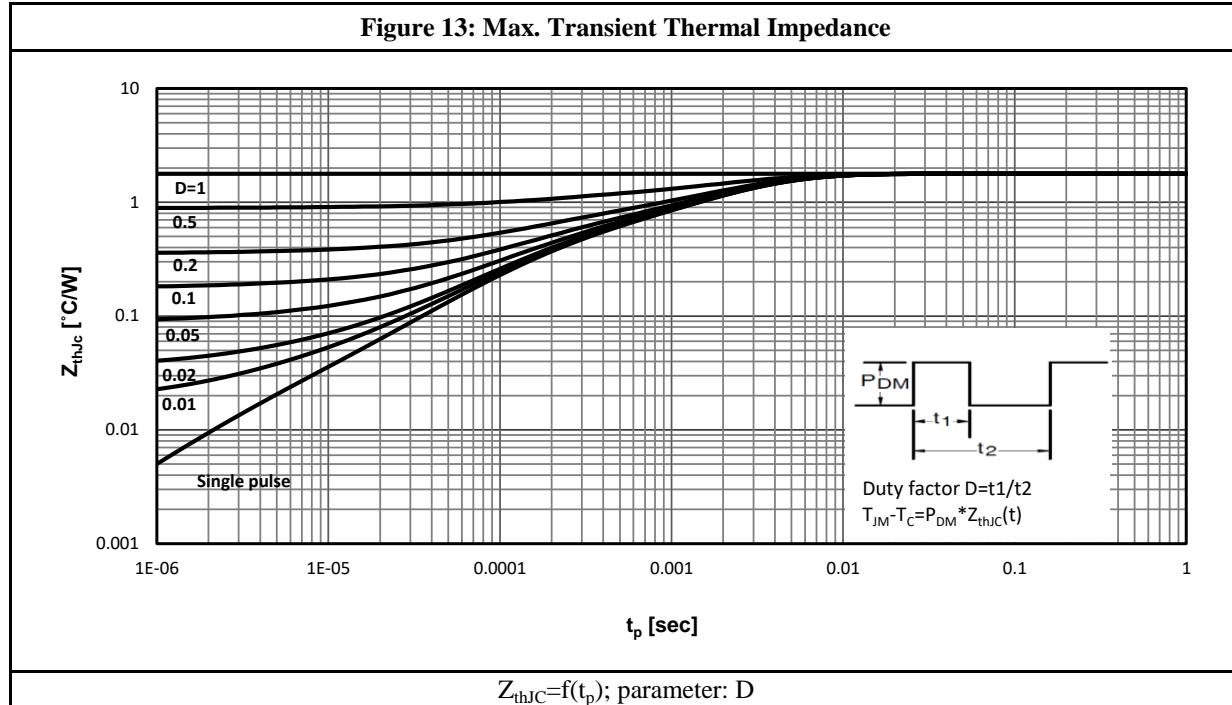
$$I_D=f(T_C);$$

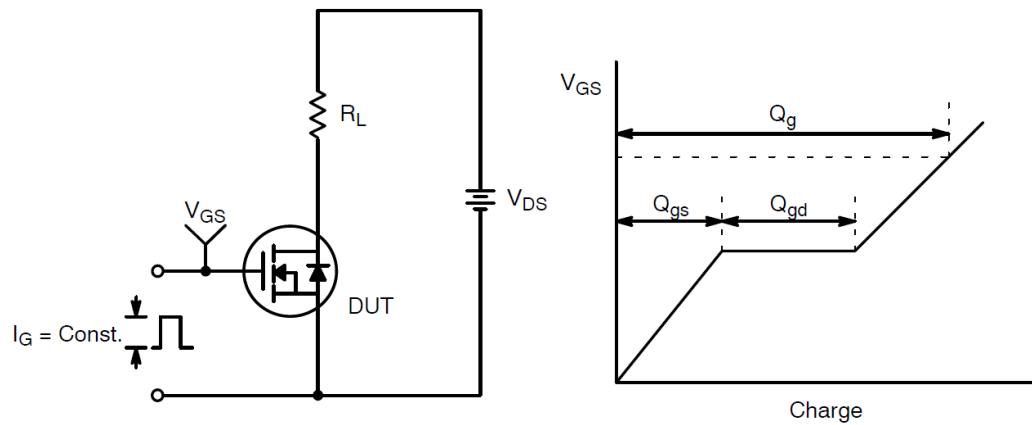
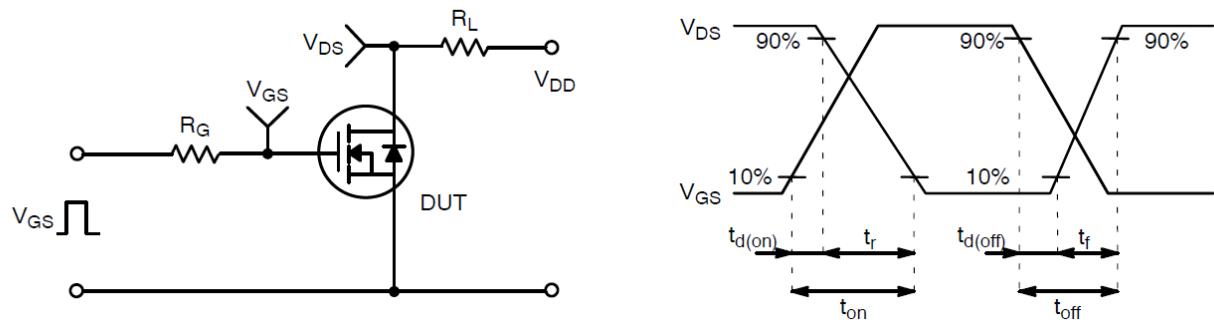
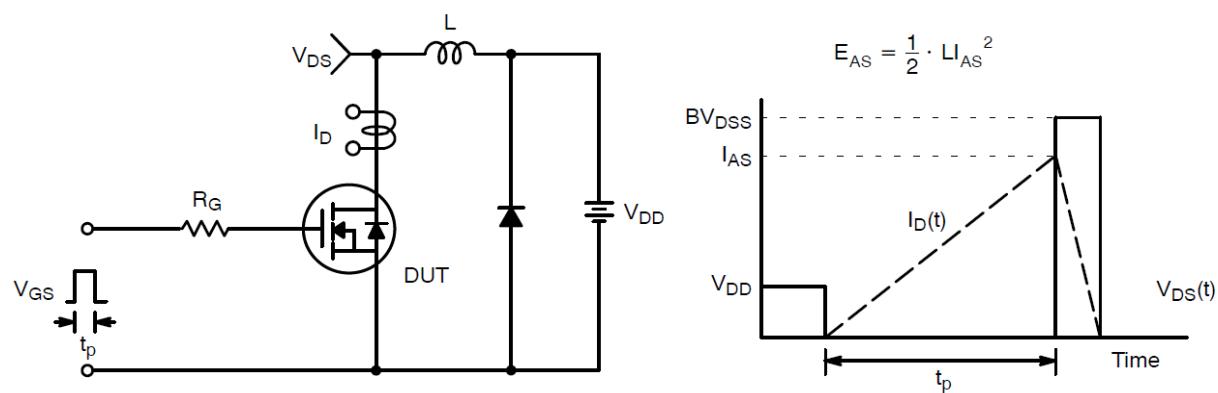
Figure 11: Safe operating area

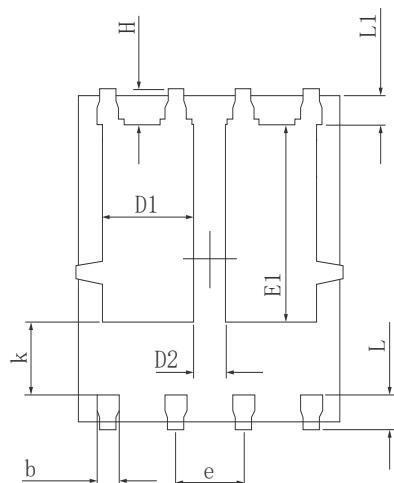
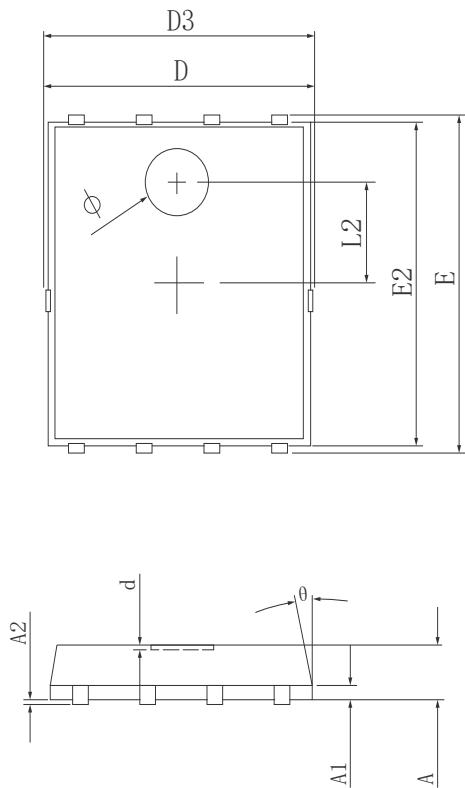
$$I_D=f(V_{DS}); \quad T_C=25 \text{ } ^\circ\text{C}; \quad D=0; \quad \text{parameter: } tp$$

Figure 12: Typ. forward characteristics

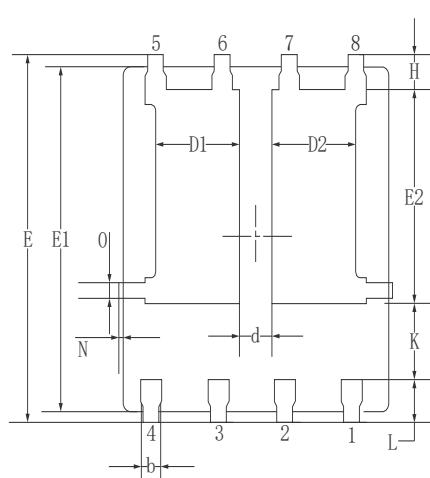
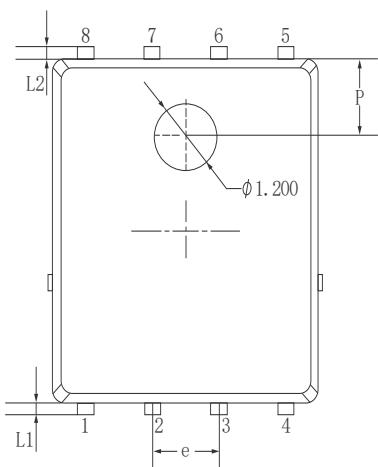
$$I_F=f(V_{SD});$$

Figure 13: Max. Transient Thermal Impedance

Test Circuit & Waveform:**Figure 14: Gate Charge Test Circuit & Waveform****Figure 15: Resistive Switching Test Circuit & Waveforms****Figure 16: Unclamped Inductive Switching Test Circuit & Waveforms**

•Dimensions (PDFN5*6)


SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	0.900	1.000	1.100
A1	0.254	REF.	
A2	0~0.05		
D	4.824	4.900	4.976
D1	1.605	1.705	1.805
D2	0.500	0.600	0.700
D3	4.924	5.000	5.076
E	5.924	6.000	6.076
E1	3.375	3.475	3.575
E2	5.674	5.750	5.826
b	0.350	0.400	0.450
e	1.270 TYP.		
L	0.534	0.610	0.686
L1	0.424	0.500	0.576
L2	1.800 REF.		
k	1.190	1.290	1.390
H	0.549	0.625	0.701
θ	8°	10°	12°
ϕ	1.100	1.200	1.300
d			0.100

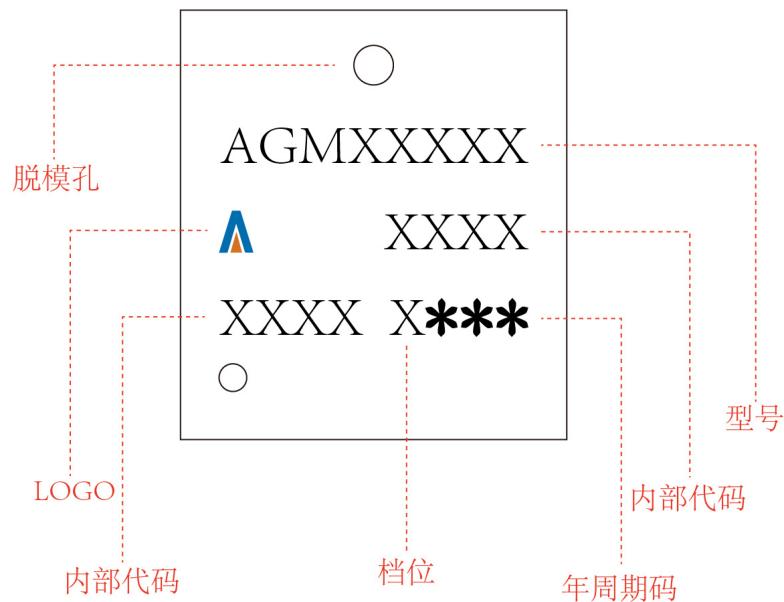


Symbol	Millimeters		
	MIN.	NOM.	MAX.
A	0.90	1.05	1.20
b	0.35	0.40	0.50
C	0.20	0.25	0.35
D	4.90	5.05	5.20
D1/D2	1.51	1.61	1.71
d	0.50	0.60	0.70
E	6.00	6.15	6.30
E1	5.60	5.75	5.90
E2	3.47	3.57	3.67
e	1.27 BSC.		
H	0.48	0.58	0.68
K	1.17	1.27	1.37
L	0.64	0.74	0.84
L1/L2	0.20 REF.		
θ	8°	10°	12°
M	0.08 REF.		
N	0	-	0.15
O	0.25 REF.		
P	1.28 REF.		

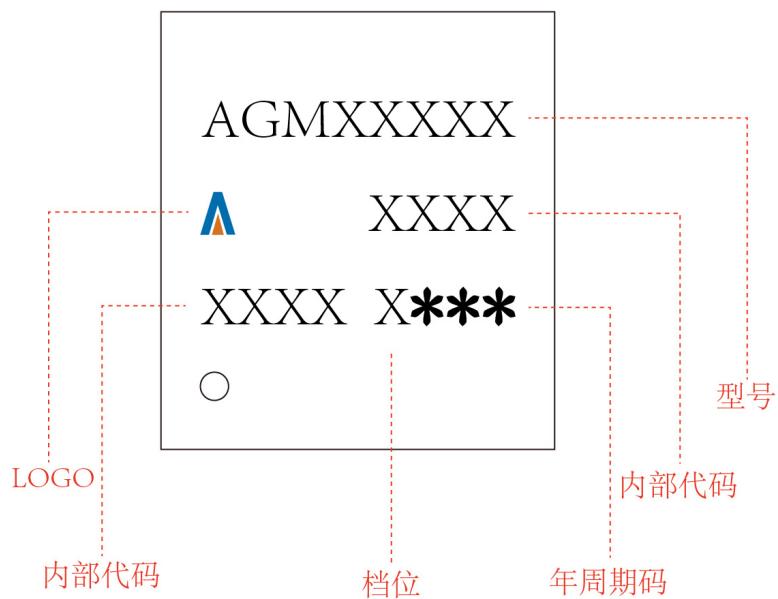
PDFN5*6

Marking Instructions:

Model1:



Model2:



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